



Material Content Data Sheet



Sales Product Name				BSC320N20NS3 G		Issued		31. July 2018	
MA#				MA000680472					
Package				PG-TDSON-8-1		Weight*		122.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.425	3.62	3.62	36212	36212	
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		93		
	non noble metal	iron	7439-89-6	0.038	0.03		309		
	non noble metal	copper	7440-50-8	37.762	30.89	30.93	308996	309398	
	non noble metal	copper	7440-50-8	0.065	0.05	0.05	535	535	
wire	non noble metal	copper	7440-50-8	0.065	0.05	0.05	535	535	
encapsulation	organic material	carbon black	1333-86-4	0.080	0.07		652		
	plastics	epoxy resin	-	5.660	4.63		46314		
	inorganic material	silicondioxide	60676-86-0	34.119	27.92	32.62	279190	326156	
leadfinish	non noble metal	tin	7440-31-5	1.452	1.19	1.19	11879	11879	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1354	1354	
solder	non noble metal	tin	7440-31-5	0.070	0.06		570		
	noble metal	silver	7440-22-4	0.087	0.07		713		
	non noble metal	lead	7439-92-1	3.328	2.72	2.85	27235	28518	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	iron	7439-89-6	0.011	0.01		93		
	non noble metal	copper	7440-50-8	11.320	9.26	9.27	92630	92751	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		55		
	non noble metal	iron	7439-89-6	0.022	0.02		183		
	noble metal	silver	7440-22-4	1.289	1.06		10551		
	non noble metal	copper	7440-50-8	22.292	18.24	19.33	182408	193197	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com